

TECHNICAL DATASHEET



Brazing alloy BrazeTec 2009

TD EN 2009 REV. 4

Composition (% in weight)

Ag	Cu	Zn	Sn	Si	Р	Mn	Ni	Other	ISO 17672:20 10	EN 1044:1999	ISO 3677
20	44	35,8 5	-	0,15	-	-	-	-	-	AG 206	-

Technical data:

Melting range (°C)	690-810			
Working temperature (°C)	810			
Melting range according to DSC measurement (°C)	-			
Min. brazing temperature (°C)	-			
Electrical conductibility (m/ Ω mm ²)	10,6			
Elongation %	25			
Density (g/cm³)	8,7			
Shear strength (MPa)	-			
Tensile strength DIN EN 12797 (MPa)	with St 37: 380; with St 50: 430			
Operating temperature of brazed joint (min/max) \pm (°C)	200			

Applications

Refrigeration, air conditioning and electrical industry, plumbing technology

Operating conditions

Silver based brazing alloy with excellent flow, capillarity and mechanical strength characteristics. Used for brazing any steels, copper and copper alloys, as well as nickel and nickel alloys.

Recommended fluxes

N1/T, Super 1, N2/E, H paste, H sprayable, RS/A, FN/E, D 98, H 280

Heat sources

Induction heating, flame, furnace in vacuum and under protective atmosphere

Delivery forms

Wire, rods, ribbon, rings, preforms, powder

Notes

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